

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
29 November 2007 (29.11.2007)

PCT

(10) International Publication Number
WO 2007/136941 A3

(51) **International Patent Classification:**
HOIL 23/34 (2006.01)

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(21) **International Application Number:**
PCT/US2007/066367

(81) **Designated States** (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW

(22) **International Filing Date:** 11 April 2007 (11.04.2007)

(25) **Filing Language:** English

(26) **Publication Language:** English

(30) **Priority Data:**
60/802,182 19 May 2006 (19.05.2006) US
11/625,100 19 January 2007 (19.01.2007) US

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(84) **Designated States** (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

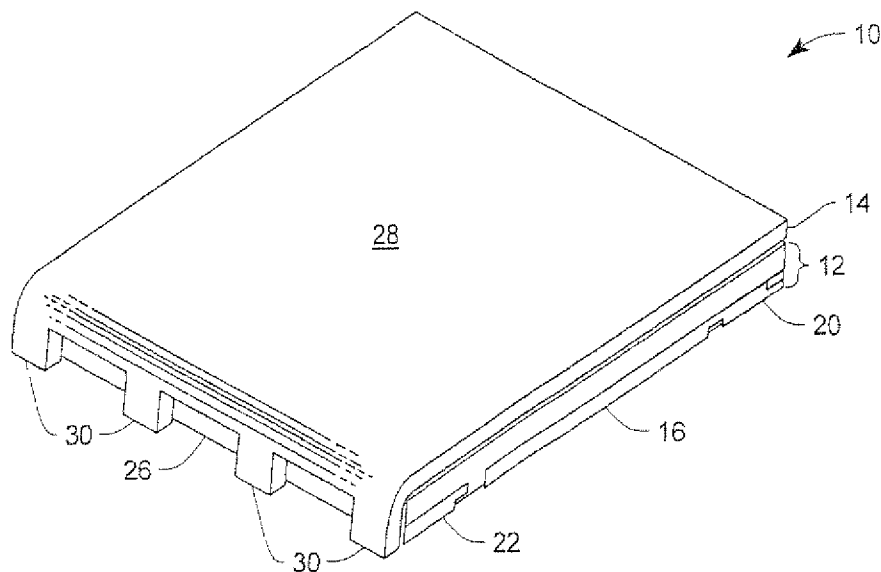
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Published:
— with international search report

[Continued on next page]

(54) **Title:** FLIP CHIP MLP WITH FOLDED HEAT SINK



(57) **Abstract:** A semiconductor package assembly including a molded leadless package (MLP) having an exposed top emitter pad and an exposed bottom source pad. A folded heat sink is attached to the exposed top emitter pad of the MLP by a soft solder attach process. The folded heat sink has a planar member generally coextensive in size with the MLP and in electrical and thermal contact with the top emitter pad of the MLP, and also has one or more leads extending generally perpendicularly to the planar member in a direction towards the lower surface of the MLP. These heat sink leads may provide the emitter connection to a printed circuit (PC) board.

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— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
10 April 2008

INTERNATIONAL SEARCH REPORT

International application No.
PCT/US07/66367

A. CLASSIFICATION OF SUBJECT MATTER

IPC(8) - H01L 23/34 (2007.01)
USPC - 257/675

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
IPC(8) - H01L 23/34, 23/495 (2007.01)
USPC - 257/675, 707

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)
USPTO EAST System (US, USPG-PUB, USOCR), MicroPatent

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	US 6,891,256 B2 (JOSHI et al) 10 May 2005 (10.05.2005) entire document	1-9
Y	US 2003/0001244 A1 (ARAKI et al) 02 January 2003 (02.01.2003) entire document	1-9
Y	US 6,777,800 B2 (MADRID et al) 17 August 2004 (17.08.2004) entire document	1-9
Y	US 6,040,626 A (CHEAH et al) 21 March 2000 (21.03.2000) entire document	2, 4
Y	US 4,960,236 A (HEDGES et al) 02 October 1990 (02.10.1990) entire document	2, 4
Y	US 5,062,896 A (HUANG et al) 05 November 1991 (05.11.1991) entire document	5
Y	US 2006/0001135 A1 (TANAKA) 05 January 2006 (05.01.2006) entire document	8
Y	US 4,554,575 A (LUCAS) 19 November 1985 (19.11.1985) entire document	8
Y	US 5,726,861 A (OSTREM) 10 March 1998 (10.03.1998) entire document	8

Further documents are listed in the continuation of Box C.

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♦ Special categories of cited documents	"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
"A" document defining the general state of the art which is not considered to be of particular relevance	"X" document of particular relevance, the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
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"O" document referring to an oral disclosure, use, exhibition or other means	
"P" document published prior to the international filing date but later than the priority date claimed	

Date of the actual completion of the international search
02 October 2007

Date of mailing of the international search report

08 FEB 2008

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PCT H₁pd₁sk. 571-272-4300
PCTOSP 571-272-7774

